## ABSTRACT

Electroplating in instrument manufacture. The development process galvanic copper plating pre printed wiring boards.

Hlushko B. - Kyiv: NTUU "KPI", ChTP, EC-11

Diploma project, 2015. Number of pages - 105 and tables - 29, pictures - 3, literature - 12.

In the project developed a manufacturing process prior galvanic copper plating printed wiring boards using sulphate electrolyte with additives such Grundeinebner Cupracid BL-CT and Glanzzusatz Cupracid BL. This electrolyte is characterized by high scattering ability, uniform distribution of copper on the surface of the board, regardless of its size, very strong layer with low internal tensions. For electroplating selected and designed the two positional galvanic baths of automatic line "Dina plus 130" with a capacity of 105 000 PCB / year.

The project envisages measures for safety and automation of process parameters, the proposed method of sewage treatment by reagent method, the main technical and economic indicators was calculated.

Keywords: copper plating, current density, plating baths, a current source, print circuit board, sulfate electrolyte, front galvanic copper plating.

Змн.	Арк.	№ докум.	Підпис	Дата